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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/814,682	03/31/2004	Wen Lin	LIN 13-38	8308
47396	7590 12/07/2006	•	EXAMINER	
HITT GAINES, PC			· MALDONADO, JULIO J	
AGERE SYST PO BOX 8325		-8-	ART UNIT	PAPER NUMBER
RICHARDSO	N, TX 75083		2823	
	•		DATE MAILED: 12/07/2000	6

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	_			
	10/814,682	LIN ET AL.				
Office Action Summary	Examiner	Art Unit	_			
, and the second	Julio J. Maldonado	2823				
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address				
A SHORTENED STATUTORY PERIOD FOR REPL WHICHEVER IS LONGER, FROM THE MAILING D.  - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tin will apply and will expire SIX (6) MONTHS from a, cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1)⊠ Responsive to communication(s) filed on 23 C	october 2006.					
	s action is non-final.					
3) Since this application is in condition for allowa	nce except for formal matters, pro	secution as to the merits is				
closed in accordance with the practice under E	Ex parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.				
Disposition of Claims						
4) Claim(s) <u>21,23-27 and 37-40</u> is/are pending in	the application.					
4a) Of the above claim(s) is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.						
6) Claim(s) 21, 23-27 and 37-40 is/are rejected.						
7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/o	r election requirement.					
Application Papers						
9) The specification is objected to by the Examine	er					
10)☐ The drawing(s) filed on is/are: a)☐ acc		Examiner.				
Applicant may not request that any objection to the						
Replacement drawing sheet(s) including the correct						
11)☐ The oath or declaration is objected to by the Ex	caminer. Note the attached Office	Action or form PTO-152.				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a)	-(d) or (f).				
a) ☐ All b) ☐ Some * c) ☐ None of:						
1. Certified copies of the priority document						
2. Certified copies of the priority document	• •					
3. Copies of the certified copies of the prior		d in this National Stage				
application from the International Bureau * See the attached detailed Office action for a list	' ''	d				
occ the attached detailed office action for a list	or the certified copies not receive	u.				
Attachment(s)						
Notice of References Cited (PTO-892)	4) Interview Summary					
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08)	Paper No(s)/Mail Da 5) Notice of Informal P					
Paper No(s)/Mail Date	6) Other:	atom reproducti				

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#### **DETAILED ACTION**

#### Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 10/23/2006 has been entered.

### Claim Rejections - 35 USC § 112

- 2. The following is a quotation of the first paragraph of 35 U.S.C. 112:
  - The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.
- 3. Claims 21, 23-27 and 37-40 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. In amended claims 21, and 37, Applicants recite, "...a buried layer substantially of germanium located over a doped substrate...". However, while there is a support for a co-doped germanium layer comprising silicon doped with germanium (Instant paragraphs [0048] [0055]), there is no support in the submitted disclosure nor in the original claims for a "buried layer substantially of germanium", making amended claims 21 and 37 lack written description.

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# Claim Objections

4. Claim 37 is objected to because of the following informalities: In claim 37, where applicants recite "...a buried layer located over a doped substrate, said buried layer doped throughout with germanium and a p-type dopant...interconnects located within interlevel dielectric layers located over said transistors, which *connect* said transistors to form an operation integrated circuit", change to -- a buried layer located over a doped substrate, said buried layer doped throughout with germanium and a p-type dopant...interconnects located within interlevel dielectric layers located over said transistors, *which provide connection to* said transistors to form an operation integrated circuit--. Appropriate correction is required.

## Claim Rejections - 35 USC § 103

- 5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 6. Claims 21 and 23-27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ouyang et al. (U.S. 6,319,799 B1, hereinafter Ouyang) in view of Bean et al. (U.S. 4,879,256, hereinafter Bean).

In reference to claims 21, 23, Ouyang (Figs.1-2C) teaches a transistor structure including a doped silicon substrate (10); a buried layer (30) made of silicon germanium having the general formula Si<sub>1-x</sub>Ge<sub>x</sub> doped with germanium and boron (Fig.2B); a doped silicon epitaxial layer (34) over said buried layer (30); and a transistor structure (16, 18,

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20, 22, 24) formed over said silicon epitaxial layer (34) (Ouyang, column 2, line 22 – column 3, line 65).

Ouyang fails to disclose wherein the buried layer is substantially germanium. However, Ouyang is open to form Si<sub>1-x</sub>Ge<sub>x</sub> at any ratio. Furthermore, Bean (Figs.1 and 4) teaches a transistor structure including a substrate (1); a buried layer made of silicon germanium and having the formula Si<sub>1-x</sub>Ge<sub>x</sub>, wherein x is between 0 and 1; an upper layer (7) made of silicon; and a transistor structure (G) formed over said upper layer (7) (Bean, column 2, line 52 – column 3, line 21). Therefore, Bean is open to a buried layer substantially of germanium.

It would have been within the scope of one of ordinary skill in the art to combine the teachings of Ouyang and Bean to enable the buried layer of Ouyang according to the teachings of Bean because one of ordinary skill in the art at the time the invention was made would have been motivated to look to alternative suitable materials for the buried layer of Ouyang and art recognized suitability for an intended purpose has been recognized to be motivation to combine. MPEP 2144.07.

In reference to claims 24, 25, the combination of Ouyang and Bean substantially teach all aspects of the invention but fails to disclose wherein the boron concentration of the co-doped germanium buried layer ranges from about 1x10<sup>15</sup> atoms/cm<sup>3</sup> to about 1x10<sup>20</sup> atoms/cm<sup>3</sup>, a dopant concentration of the doped substrate ranges from about 1x10<sup>14</sup> atoms/cm<sup>3</sup> to about 1x10<sup>15</sup> atoms/cm<sup>3</sup>, and a dopant concentration of the doped epitaxial layer ranges from about 1x10<sup>14</sup> atoms/cm<sup>3</sup> to about 1x10<sup>15</sup> atoms/cm<sup>3</sup>.

However, the selection of the selected dope ranges is obvious because it is a matter of

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determining optimum process condition by routine experimentation with a limited number of species to obtain a desired dopant concentration on the substrate, germanium layer and the epitaxial layer. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use the combination of Ouyang and Bean to arrive at the claimed invention.

In reference to claims 26 and 27, the combined teachings of Ouyang and Bean substantially teach all aspects of the invention but fail to disclose wherein the co-doped germanium buried layer has a thickness ranging from about 1 µm to about 10 µm, and wherein the doped substrate, co-doped germanium buried layer, and the doped epitaxial layer collectively have a thickness ranging from about 2  $\mu$ m to about 20  $\mu$ m. Notwithstanding, it would have been an obvious matter of design choice bounded by well known manufacturing constraints and ascertainable by routine experimentation and optimization to choose these particular dimensions because applicant has not disclosed that the dimensions are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical, and it appears prima facie that the process would possess utility using another dimension. Indeed, it has been held that mere dimensional limitations are prima facie obvious absent a disclosure that the limitations are for a particular unobvious purpose, produce an unexpected result, or are otherwise critical. See, for example, In re Rose, 220 F.2d 459, 105 USPQ 237 (CCPA 1955); In re Rinehart, 531 F.2d 1048, 189 USPQ 143 (CCPA 1976); Gardner v. TEC Systems, Inc., 725 F.2d 1338, 220 USPQ 777 (Fed. Cir. 1984), cert. denied, 469 U.S. 830, 225 USPQ 232 (1984); In re Dailey, 357 F.2d 669, 149 USPQ 47 (CCPA 1966).

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7. Claims 37-40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ouyang ('799) in view of Bean ('256) and Ramadani et al. (U.S. 7,067,856 B2, hereinafter Ramadani).

In reference to claims 37, 38 and 40, Ouyang (Figs.1-2C) teaches a transistor structure including a doped silicon substrate (10); a buried layer (30) made of silicon germanium having the general formula Si<sub>1-x</sub>Ge<sub>x</sub> doped with germanium and boron (Fig.2B); a doped silicon epitaxial layer (34) over said buried layer (30); and a transistor structure (16, 18, 20, 22, 24) formed over said silicon epitaxial layer (34) (Ouyang, column 2, line 22 – column 3, line 65).

Ouyang fails to disclose wherein the buried layer is substantially germanium. However, Ouyang is open to form Si<sub>1-x</sub>Ge<sub>x</sub> at any ratio. Furthermore, Bean (Figs.1 and 4) teaches a transistor structure including a substrate (1); a buried layer made of silicon germanium and having the formula Si<sub>1-x</sub>Ge<sub>x</sub>, wherein x is between 0 and 1; an upper layer (7) made of silicon; and a transistor structure (G) formed over said upper layer (7) (Bean, column 2, line 52 – column 3, line 21). Therefore, Bean is open to a buried layer substantially of germanium.

It would have been within the scope of one of ordinary skill in the art to combine the teachings of Ouyang and Bean to enable the buried layer of Ouyang according to the teachings of Bean because one of ordinary skill in the art at the time the invention was made would have been motivated to look to alternative suitable materials for the buried layer of Ouyang and art recognized suitability for an intended purpose has been recognized to be motivation to combine. MPEP 2144.07.

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The combined teachings of Ouyang and Bean fail to expressly disclose wherein said transistor structure further includes interconnects located within interlevel dielectric layers located over transistors, which connect the transistors to form an operational integrated circuit and additional active and passive devices.

However, it is well-known in the art directed to MOS devices that these devices further include interconnects and other active and passive devices located within interlevel dielectric layers located over the transistors, which connect the transistors to form an operational integrated circuit. Further support can be in Ramdani (Figs.7-11 and column 13, line 38 – column 16, line 21). Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made that the device of the combination of Ouyang and Bean would also include the claimed limitations as is well-known or as supported by the teachings of Ramdani.

In reference to claim 39, the combination of Ouyang Bean and Ramdani substantially teach all aspects of the invention but fails to disclose wherein the boron concentration of the co-doped germanium buried layer ranges from about 1x10<sup>15</sup> atoms/cm³ to about 1x10<sup>20</sup> atoms/cm³, a dopant concentration of the doped substrate ranges from about 1x10<sup>14</sup> atoms/cm³ to about 1x10<sup>15</sup> atoms/cm³, and a dopant concentration of the doped epitaxial layer ranges from about 1x10<sup>14</sup> atoms/cm³ to about 1x10<sup>15</sup> atoms/cm³. However, the selection of the selected dope ranges is obvious because it is a matter of determining optimum process condition by routine experimentation with a limited number of species to obtain a desired dopant concentration on the substrate, germanium layer and the epitaxial layer. Therefore, it

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would have been obvious to one of ordinary skill in the art at the time the invention was made to use the combination of Ouyang, Bean and Ramdani to arrive at the claimed invention.

## Response to Arguments

8. Applicant's arguments with respect to claims 21, 23-27 and 37-40 have been considered but are most in view of the new ground(s) of rejection.

#### **Conclusion**

- 9. Applicants are encouraged, where appropriate, to check Patent Application Information Retrieval (PAIR) (http://portal.uspto.gov/external/portal/pair) which provides applicants direct secure access to their own patent application status information, as well as to general patent information publicly available.
- 10. Any inquiry concerning this communication or earlier communications from the examiner should be directed to examiner Julio J. Maldonado whose telephone number is (571) 272-1864. The examiner can normally be reached on Monday through Friday.
- 11. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew Smith, can be reached on (571) 272-1907. The fax number for this group is 571-273-8300. Updates can be found at http://www.uspto.gov/web/info/2800.htm.

MATTHEW SMITH SUPERVICORY PATENT EXAMINER TECHNOLOGY CENTER 2800

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Julio J. Maldonado November 29, 2006 Julio J. Maldonado Patent Examiner Art Unit 2823

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